

NTF3055L108, NVF3055L108

Power MOSFET

3.0 A, 60 V, Logic Level, N-Channel SOT-223

Designed for low voltage, high speed switching applications in power supplies, converters and power motor controls and bridge circuits.

Features

- NVF Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

Applications

- Power Supplies
- Converters
- Power Motor Controls
- Bridge Circuits

MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V _{DSS}	60	Vdc
Drain-to-Gate Voltage (R _{GS} = 1.0 MΩ)	V _{DGR}	60	Vdc
Gate-to-Source Voltage	V _{GS}	± 15	Vdc
– Continuous		± 20	Vpk
– Non-repetitive (t _p ≤ 10 ms)			
Drain Current	I _D	3.0	Adc
– Continuous @ T _A = 25°C (Note 1)		1.4	Apk
– Continuous @ T _A = 100°C (Note 2)		9.0	
– Single Pulse (t _p ≤ 10 μs)	I _{DM}		
Total Power Dissipation @ T _A = 25°C (Note 1)	P _D	2.1	Watts
Total Power Dissipation @ T _A = 25°C (Note 2)		1.3	Watts
Derate above 25°C		0.014	W/°C
Operating and Storage Temperature Range	T _J , T _{stg}	–55 to 175	°C
Single Pulse Drain-to-Source Avalanche Energy – Starting T _J = 25°C (V _{DD} = 25 Vdc, V _{GS} = 5.0 Vdc, I _{L(pk)} = 7.0 Apk, L = 3.0 mH, V _{DS} = 60 Vdc)	E _{AS}	74	mJ
Thermal Resistance	R _{θJA}	66	°C/W
– Junction-to-Ambient (Note 1)		75	
– Junction-to-Ambient (Note 2)			
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	T _L	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

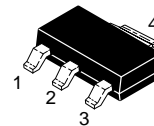
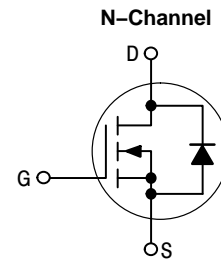
1. When surface mounted to an FR4 board using 1" pad size, 1 oz. (Cu. Area 1 in²).
2. When surface mounted to an FR4 board using minimum recommended pad size, 2 oz. (Cu. Area 0.272 in²).



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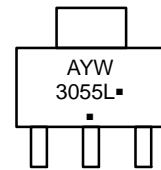
3.0 A, 60 V
R_{DS(on)} = 120 mΩ



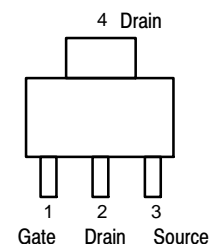
SOT-223
CASE 318E
STYLE 3

MARKING DIAGRAM

3055L = Device Code
A = Assembly Location
Y = Year
W = Work Week
▪ = Pb-Free Package
(Note: Microdot may be in either location)



PIN ASSIGNMENT



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

NTF3055L108, NVF3055L108

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage (Note 3) (V _{GS} = 0 Vdc, I _D = 250 μAdc) Temperature Coefficient (Positive)	V _{(BR)DSS}	60 –	68 68	– –	Vdc mV/°C
Zero Gate Voltage Drain Current (V _{DS} = 60 Vdc, V _{GS} = 0 Vdc) (V _{DS} = 60 Vdc, V _{GS} = 0 Vdc, T _J = 150°C)	I _{DSS}	– –	– –	1.0 10	μAdc
Gate-Body Leakage Current (V _{GS} = ± 15 Vdc, V _{DS} = 0 Vdc)	I _{GSS}	–	–	± 100	nAdc

ON CHARACTERISTICS (Note 3)

Gate Threshold Voltage (Note 3) (V _{DS} = V _{GS} , I _D = 250 μAdc) Threshold Temperature Coefficient (Negative)	V _{GS(th)}	1.0 –	1.68 4.6	2.0 –	Vdc mV/°C
Static Drain-to-Source On-Resistance (Note 3) (V _{GS} = 5.0 Vdc, I _D = 1.5 Adc)	R _{DS(on)}	–	92	120	mΩ
Static Drain-to-Source On-Resistance (Note 3) (V _{GS} = 5.0 Vdc, I _D = 3.0 Adc) (V _{GS} = 5.0 Vdc, I _D = 1.5 Adc, T _J = 150°C)	V _{DS(on)}	–	0.290 0.250	0.43 –	Vdc
Forward Transconductance (Note 3) (V _{DS} = 7.0 Vdc, I _D = 3.0 Adc)	g _{fs}	–	5.7	–	Mhos

DYNAMIC CHARACTERISTICS

Input Capacitance	(V _{DS} = 25 Vdc, V _{GS} = 0 V, f = 1.0 MHz)	C _{iss}	–	313	440	pF
Output Capacitance		C _{oss}	–	112	160	
Transfer Capacitance		C _{rss}	–	40	60	

SWITCHING CHARACTERISTICS (Note 4)

Turn-On Delay Time	(V _{DD} = 30 Vdc, I _D = 3.0 Adc, V _{GS} = 5.0 Vdc, R _G = 9.1 Ω) (Note 3)	t _{d(on)}	–	11	25	ns
Rise Time		t _r	–	35	70	
Turn-Off Delay Time		t _{d(off)}	–	22	45	
Fall Time		t _f	–	27	60	
Gate Charge	(V _{DS} = 48 Vdc, I _D = 3.0 Adc, V _{GS} = 5.0 Vdc) (Note 3)	Q _T	–	7.6	15	nC
		Q ₁	–	1.4	–	
		Q ₂	–	4.0	–	

SOURCE-DRAIN DIODE CHARACTERISTICS

Forward On-Voltage	(I _S = 3.0 Adc, V _{GS} = 0 Vdc) (I _S = 3.0 Adc, V _{GS} = 0 Vdc, T _J = 150°C) (Note 3)	V _{SD}	– –	0.87 0.72	1.0 –	Vdc
Reverse Recovery Time	(I _S = 3.0 Adc, V _{GS} = 0 Vdc, dI _S /dt = 100 A/μs) (Note 3)	t _{rr}	–	35	–	ns
		t _a	–	21	–	
		t _b	–	14	–	
Reverse Recovery Stored Charge		Q _{RR}	–	0.044	–	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.
4. Switching characteristics are independent of operating junction temperatures.

TYPICAL ELECTRICAL CHARACTERISTICS

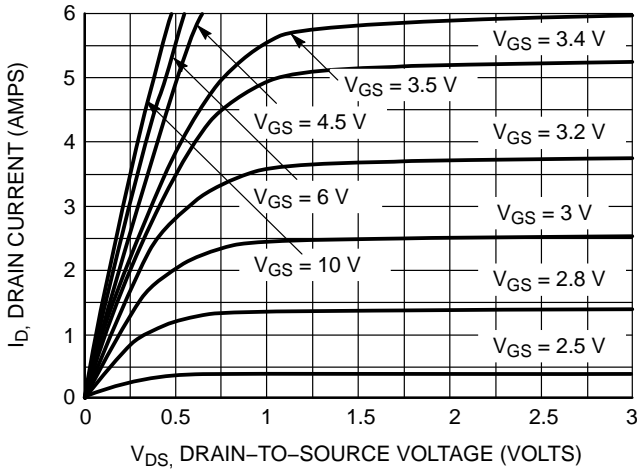


Figure 1. On-Region Characteristics

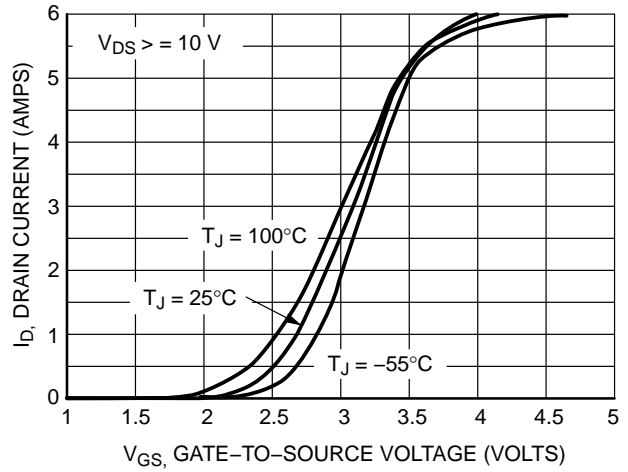


Figure 2. Transfer Characteristics

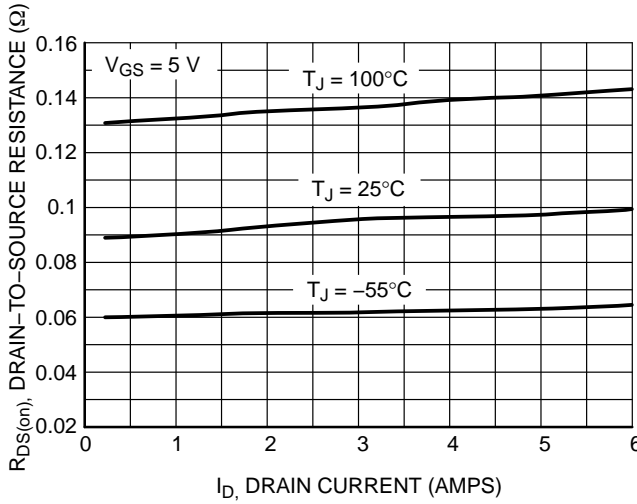


Figure 3. On-Resistance vs. Gate-to-Source Voltage

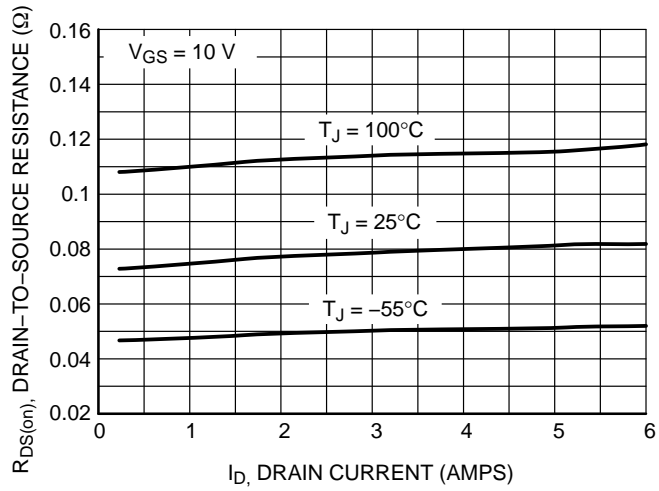


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

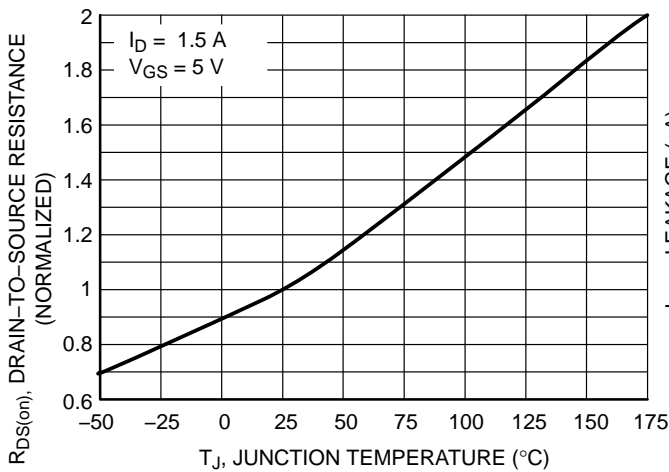


Figure 5. On-Resistance Variation with Temperature

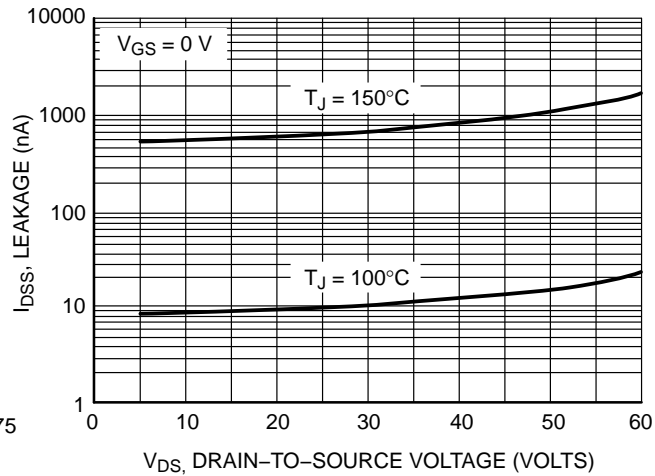


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL ELECTRICAL CHARACTERISTICS

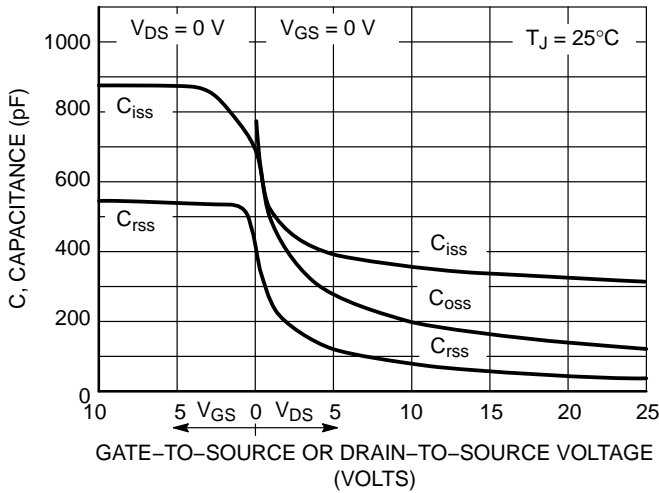


Figure 7. Capacitance Variation

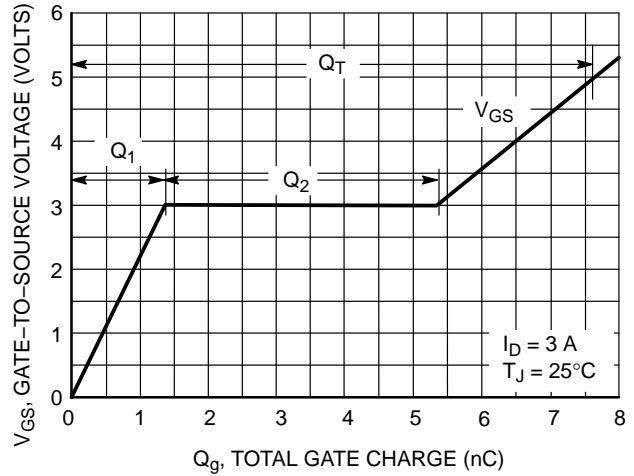


Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

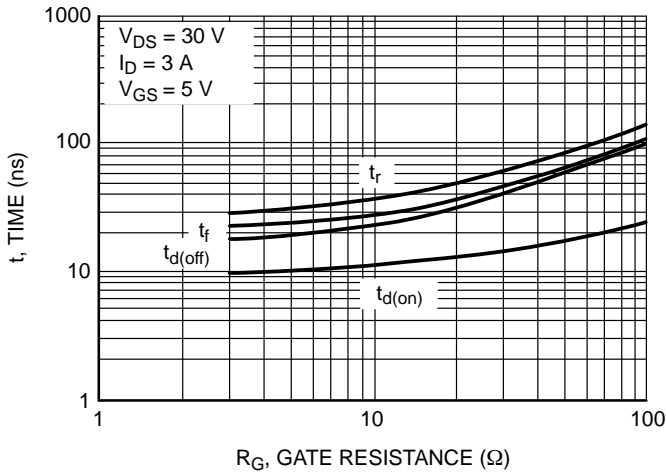


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

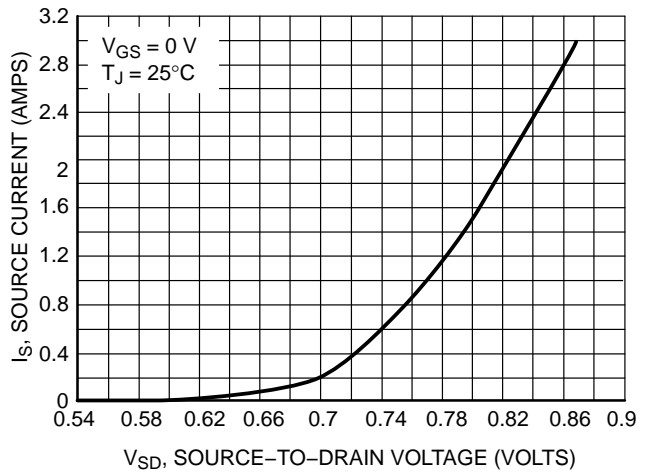


Figure 10. Diode Forward Voltage vs. Current

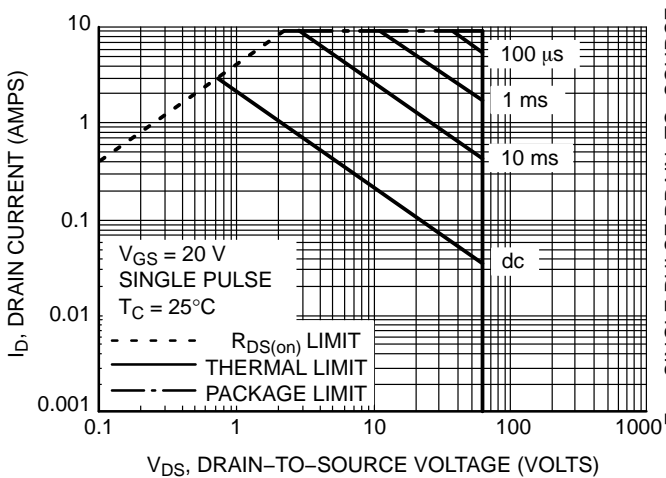


Figure 11. Maximum Rated Forward Biased Safe Operating Area

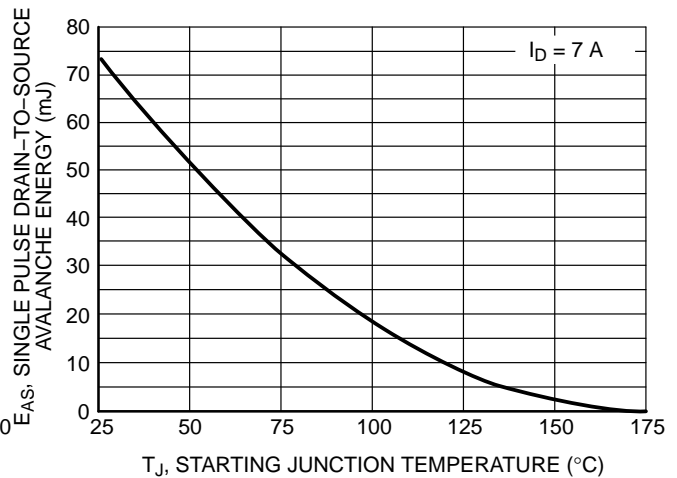


Figure 12. Maximum Avalanche Energy vs. Starting Junction Temperature

NTF3055L108, NVF3055L108

TYPICAL ELECTRICAL CHARACTERISTICS

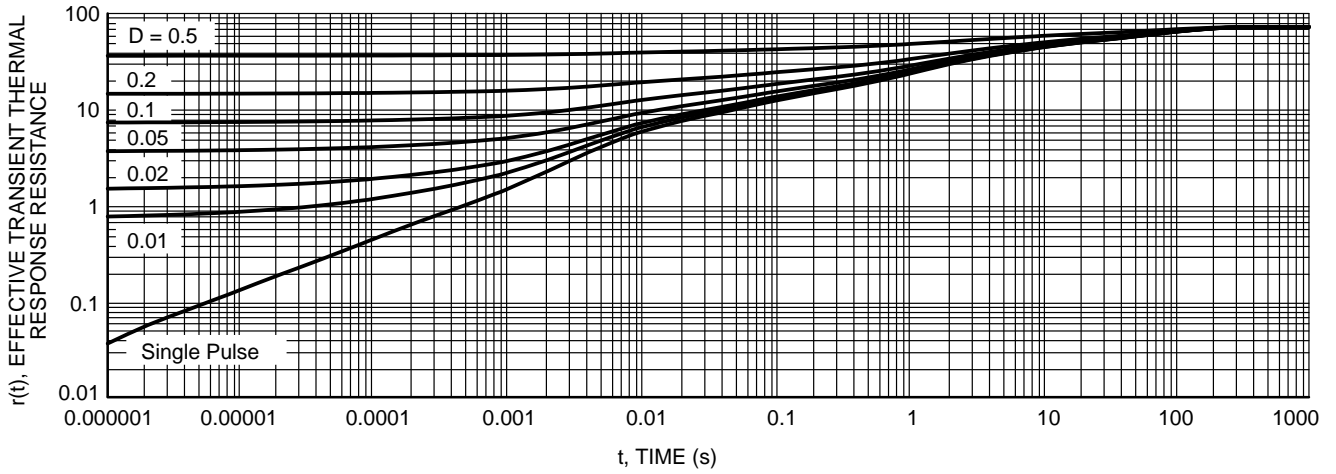


Figure 13. Thermal Response

ORDERING INFORMATION

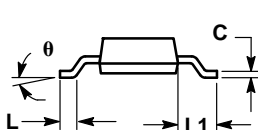
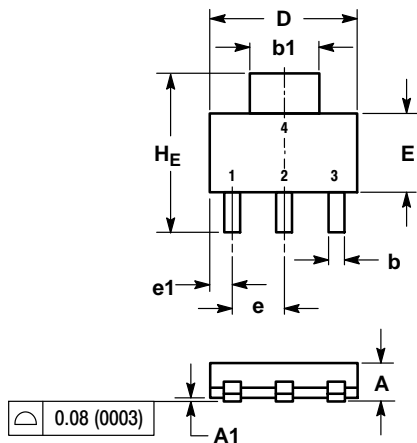
Device	Package	Shipping [†]
NTF3055L108T1G	SOT-223 (TO-261) (Pb-Free)	1000 / Tape & Reel
NVF3055L108T1G	SOT-223 (TO-261) (Pb-Free)	1000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NTF3055L108, NVF3055L108

PACKAGE DIMENSIONS

SOT-223 (TO-261)
CASE 318E-04
ISSUE N

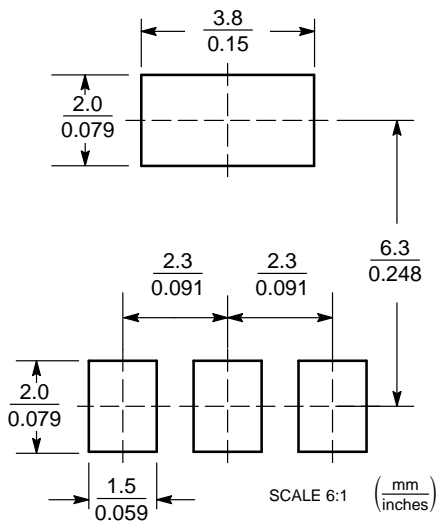


NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCH.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
c	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
e	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
L	0.20	---	---	0.008	---	---
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°	-	10°	0°	-	10°

STYLE 3:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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